

## CLAIMS

What is claimed is:

- 1 1. A system for lapping a head, comprising:
- 2 (a) a wafer including at least one head each having an electrical lapping guide (ELG),
- 3 a plurality of wafer contacts in electrical communication with the ELG, and a
- 4 closure formed thereon defining a slot in which the wafer contacts are positioned;
- 5 (b) a lapping cable coupled to a testing device, the lapping cable including a plurality
- 6 of lapping cable contacts; and
- 7 (c) an adapter including a plurality of adapter contacts in electrical communication
- 8 with the lapping cable contacts;
- 9 (d) wherein the adapter contacts are removably positionable in electrical
- 10 communication with the wafer contacts during a lapping process.
- 1 2. The system as recited in claim 1, wherein the adapter is constructed from a
- 2 polyimide material.
- 1 3. The system as recited in claim 1, wherein adapter includes a pair of holes formed
- 2 therein for coupling with a pair of holes formed in the lapping cable via a pair of
- 3 alignment pins.



- 2 (a) a wafer including at least one head each having an electrical lapping guide (ELG),  
3 a plurality of wafer contacts in electrical communication with the ELG, and a  
4 closure formed thereon defining a slot in which the wafer contacts are positioned;  
5 and  
6 (b) a lapping cable coupled to a testing device, the lapping cable including a plurality  
7 of lapping cable contacts extending outwardly therefrom;  
8 (c) wherein the lapping cable contacts are removably positionable in electrical  
9 communication with the wafer contacts during a lapping process.

1 11. The system as recited in claim 10, wherein the lapping cable includes at least one  
2 guide for being removably positioned in a slot defined by closures of adjacent  
3 heads formed on the wafer.

1 12. The system as recited in claim 10, wherein the lapping cable contacts extend in a  
2 direction perpendicular with respect to the lapping cable.

1 13. The system as recited in claim 10, wherein the lapping cable includes a recess for  
2 preventing contact with the wafer during the lapping process.

1 14. An apparatus for use with a wafer including at least one head each having an  
2 electrical lapping guide (ELG), a plurality of wafer contacts in electrical  
3 communication with the ELG, and a closure formed thereon defining a slot in  
4 which the wafer contacts are positioned, and a lapping cable coupled to a testing

5 device, the lapping cable including a plurality of lapping cable contacts; the  
6 apparatus comprising: an adapter including a plurality of adapter contacts in  
7 electrical communication with the lapping cable contacts, wherein the adapter  
8 contacts are removably positionable in electrical communication with the wafer  
9 contacts during a lapping process.

- 1 15. An apparatus for use with a wafer including at least one head each having an  
2 electrical lapping guide (ELG), a plurality of wafer contacts in electrical  
3 communication with the ELG, and a closure formed thereon defining a slot in  
4 which the wafer contacts are positioned, the apparatus comprising:  
5 (a) a lapping cable coupled to a testing device, the lapping cable including a plurality  
6 of lapping cable contacts extending outwardly therefrom in direction  
7 perpendicular with respect to the lapping cable;  
8 (b) wherein the lapping cable contacts are removably positionable in electrical  
9 communication with the wafer contacts during a lapping process.

- 1 16. An adapter including a plurality of adapter contacts in electrical communication  
2 with a plurality of lapping cable contacts of <sup>the</sup> ~~the lapping cable~~, wherein the adapter  
3 contacts are removably positionable in electrical communication with a plurality  
4 of wafer contacts of a wafer during a lapping process.

- 1 17. A lapping cable coupled to a testing device and including a plurality of lapping  
2 cable contacts extending outwardly therefrom in a direction perpendicular with

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3 respect to the lapping cable, wherein the lapping cable contacts are removably  
4 positionable in electrical communication with a plurality of wafer contacts of a  
5 wafer during a lapping process.

1 18. An adapter including a plurality of adapter contacts in electrical communication  
2 with a plurality of lapping cable contacts of <sup>(the lapping cable)</sup>, the adapter further  
3 including at least one guide for being removably positioned in a slot defined by  
4 closures of adjacent heads formed on the wafer, and a recess for preventing  
5 contact with the wafer during the lapping process, wherein the adapter contacts  
6 are removably positionable in electrical communication with a plurality of wafer  
7 contacts of the wafer during a lapping process.

1 19. A method for testing during a lapping process, comprising:  
2 (a) providing an adapter including a plurality of adapter contacts in electrical  
3 communication with a plurality of lapping cable contacts of the lapping cable;  
4 (b) removably positioning the adapter contacts of the adapter in electrical  
5 communication with a plurality of wafer contacts of a wafer;  
6 (c) lapping a surface of the wafer; and  
7 (d) measuring a head of the wafer during the lapping process.